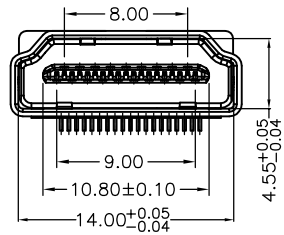
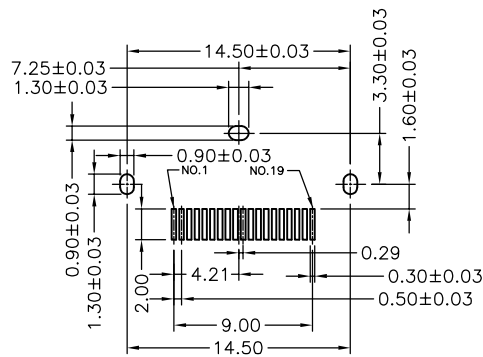
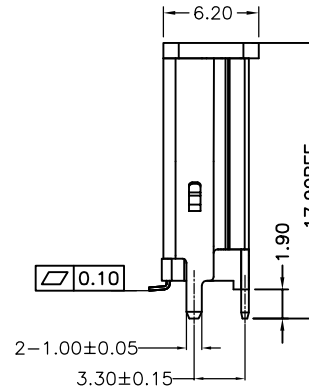
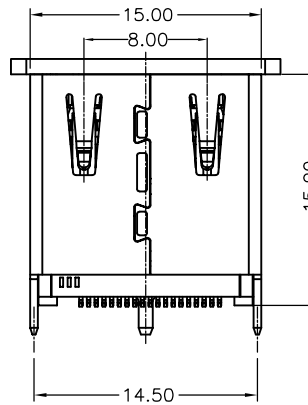
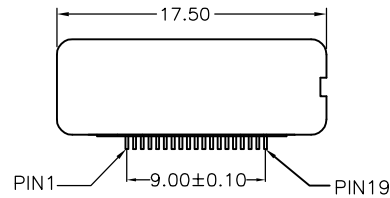
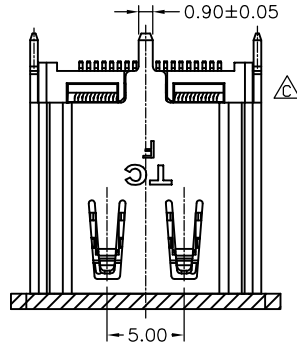


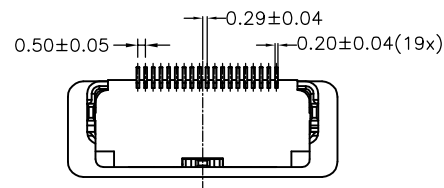
THE PART MEETS TECONN "GPO01" COMPLIANCE NEW REV.



WITHOUT COVER



RECOMMENDED PCB LAYOUT(T=1.60mm)
TOP VIEW




NOTE:

- 1.MATERIAL:
HOUSING AND BRACKET: HIGH TEMP.THERMOPLASTIC, UL 94V-0
COLOR: BLACK.
CONTACT: COPPER ALLOY, THICKNESS=0.20MM
SHIELD: COPPER ALLOY, THICKNESS=0.50MM
- 2.FINISH:
CONTACT: GOLD PLATING ON CONTACT AREA SEE NOTE
G/F PLATED ON SOLDER TAILS
50u" MIN. NICKEL UNDER PLATED OVER ALL
SHIELD: 50u" MIN. NICKEL PLATED OVER ALL
- 3.MECHANICAL CHARACTERISTICS
INSERTION FORCE: 44.1N MAX
EXTROCTION FORCE: 9.8N MIN, 39.2N MAX
MATING CYCLE:10000 CYCLES
- 4.ELECTRICAL CHARACTERISTICS
RATING CURRENT: 0.5A
RATING VOLTAGE: 40V
CONTACT RESISTANCE: 10 MILLIOHMS MAX
(EXCLUDING CONDUCTOR RESISTANCE)
INSULATION RESISTANCE:
a, UNMATED: 100M OHMS MIN AT 500 VDC
b, MATED: 10M OHMS MIN AT 150 VDC
DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/1MINUTE
OPERATING TEMPERATURE: -20°C---+85°C
STORAGE TEMPERATURE: -20°C---+65°C

FORM		PART NO. INFORMATION		PACKING TYPE	
A:ASS'y	11:HDMI-A/F	A111947-F-XX-X	T: TRAY	R: TAPE REEL	CONTACT AREA PLATING
	NUMBER OF POS.	19	01:Au 1u"	03:Au 3u"	05:Au 5u"
	FOLLOW NO.	47	10:Au 10u"	15:Au 15u"	
	DIFFERENCE TYPE				

Item	Title	Material	Dispose	Remark
1	Terminal	Copper Alloy	Mating Area:See P/N Solder Tails:Sn	t=0.20
2	Molding	LCP	UL94V-0	Black
3	Shell	Copper Alloy	Ni:50u" Min.	t=0.50
4	CAP	LCP	UL94V-0	Black

C	TE2018-0094	更新视图	Cola	2018/08/17
B	TE2011-0376	修正料号		2011/07/21
A	TE2010-0628	NEW RELEASE		2011/11/08
REV	ECN NO	DESCRIPTION	DESIGN	DATE

X. ± 0.35	APPD:	Henry Sun	TITLE:	 泰康电子 TECONN
.X ± 0.25	CHKD:	Lebon Lee	HDMI-A/F 180° SMT H=15/19PIN/脚长1.90 (INSERTMOLDING)	
.XXX±	DR:	Cola Lee	PART NO:	
X* ± 2'			A111947-F-XX-X	
X* ± 1.5'			DWG NO:	CUSTOMER DRAWING
	UNITS:	mm	SCALE:	1:1
				SHEET:10F1
				REV: C